



SLOVENSKI STANDARD
SIST EN IEC 61188-6-1:2021

01-oktober-2021

Nadomešča:
SIST EN 61188-5-1:2003

Plošče tiskanih vezij in sestavi plošč tiskanih vezij - Zasnova in uporaba - 6-1. del: Razmestitev priključkov - Osnovne zahteve za razmestitev priključkov na tiskanih vezjih

Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements for land pattern on circuit boards

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Ta slovenski standard je istoveten z: EN IEC 61188-6-1:2021

ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards
plošče

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EUROPEAN STANDARD

EN IEC 61188-6-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2021

ICS 31.180; 31.190

Supersedes EN 61188-5-1:2002 and all of its
amendments and corrigenda (if any)

English Version

Circuit boards and circuit board assemblies - Design and use -
Part 6-1: Land pattern design - Generic requirements for land
pattern on circuit boards
(IEC 61188-6-1:2021)

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-1: Conception de la zone
de report - Exigences génériques pour la zone de report sur
les cartes imprimées
(IEC 61188-6-1:2021)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-1: Anschlussflächengestaltung -
Allgemeine Anforderungen an die Anschlussflächenstruktur
auf Leiterplatten
(IEC 61188-6-1:2021)

This European Standard was approved by CENELEC on 2021-03-30. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61188-6-1:2021 (E)**European foreword**

The text of document 91/1636/CDV, future edition 1 of IEC 61188-6-1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61188-6-1:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-03-30

This document supersedes EN 61188-5-1:2002 and all of its amendments and corrigenda (if any).

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Endorsement notice**iTeh STANDARD PREVIEW**

The text of the International Standard IEC 61188-6-1:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61188-5-1:2002	NOTE	Harmonized as EN 61188-5-1:2002 (not modified)
IEC 61188-5-2:2003	NOTE	Harmonized as EN 61188-5-2:2003 (not modified)
IEC 61188-5-3:2007	NOTE	Harmonized as EN 61188-5-3:2007 (not modified)
IEC 61188-5-4:2007	NOTE	Harmonized as EN 61188-5-4:2007 (not modified)
IEC 61188-5-5:2007	NOTE	Harmonized as EN 61188-5-5:2007 (not modified)
IEC 61188-5-6:2003	NOTE	Harmonized as EN 61188-5-6:2003 (not modified)
IEC 61188-5-8:2007	NOTE	Harmonized as EN 61188-5-8:2008 (not modified)
IEC 61188-6-2	NOTE	Harmonized as EN IEC 61188-6-2
IEC 61760-1	NOTE	Harmonized as EN IEC 61760-1

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61191-1	-	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN IEC 61191-1	-
IEC 61191-2	2017	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	2017
IEC 61191-3	-	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	-
IEC 61191-4	-	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	-
IEC 61760-3	-	Surface mounting technology - Part 3: Standard method for the specification of components for through-hole reflow (THR) soldering	EN IEC 61760-3	-

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IEC 61188-6-1

Edition 1.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Circuit boards and circuit board assemblies – Design and use –
Part 6-1: Land pattern design – Generic requirements for land pattern on
circuit boards**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-1: Conception de la zone de report – Exigences génériques pour la zone
de report sur les cartes imprimées**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.180; 31.190

ISBN 978-2-8322-9443-7

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SIST EN IEC 61188-6-1:2021

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES –
DESIGN AND USE –****Part 6-1: Land pattern design –
Generic requirements for land pattern on circuit boards**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 61188-6-1 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This first edition cancels and replaces the first edition of IEC 61188-5-1 published in 2002, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The content is completely updated to reflect current industry requirements. See Introduction.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1636/CDV	91/1671/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61188 series, published under the general title *Circuit boards and circuit board assemblies – Design and use*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

Explanation why the following standards will be replaced by the new IEC 6188-6 series:

IEC 61188-5-1:2002, *Printed boards and printed board assemblies – Design and use – Part 5-1: Attachment (land/joint) considerations – Generic requirements*

IEC 61188-5-2:2003, *Printed boards and printed board assemblies – Design and use – Part 5-2: Attachment (land/joint) considerations – Discrete components*

IEC 61188-5-3:2007, *Printed boards and printed board assemblies – Design and use – Part 5-3: Attachment (land/joint) considerations – Components with gull-wing leads on two sides*

IEC 61188-5-4:2007, *Printed boards and printed board assemblies – Design and use – Part 5-4: Attachment (land/joint) considerations – Components with J leads on two sides*

IEC 61188-5-5:2007, *Printed boards and printed board assemblies – Design and use – Part 5-5: Attachment (land/joint) considerations – Components with gull-wing leads on four sides*

IEC 61188-5-6:2003, *Printed boards and printed board assemblies – Design and use – Part 5-6: Attachment (land/joint) considerations – Chip carriers with J-leads on four sides*

IEC 61188-5-8:2007, *Printed board and printed board assemblies – Design and use – Part 5-8: Attachment (land/joint) considerations – Area array components (BGA, FBGA, CGA, LGA)*

Content is mostly equivalent to IPC-782A with Amendments 1 and 2, which was replaced in 2002 by IPC-7351. The component spectrum and pitch levels have dramatically increased since publication of the IEC 61188-5 (all parts) and the dimensioning concept does no longer fulfil the mounting and soldering requirements.

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